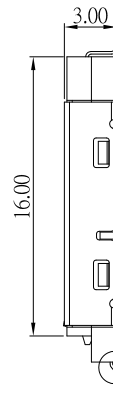
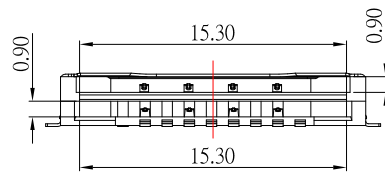
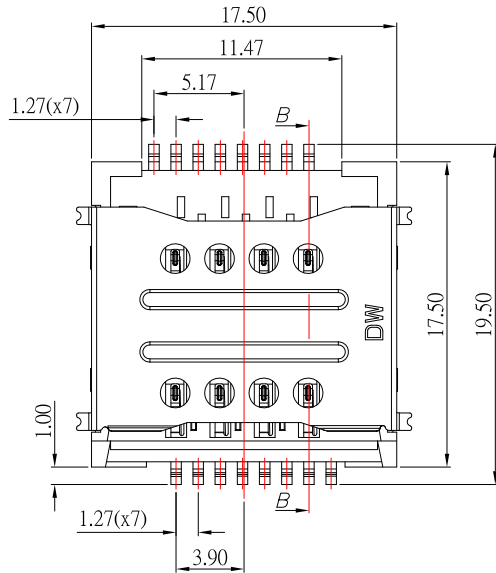
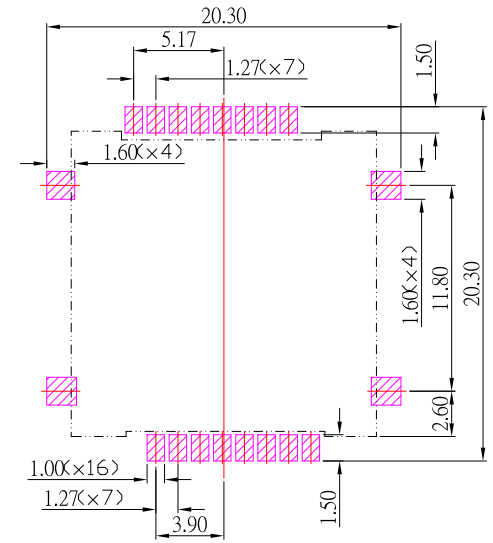
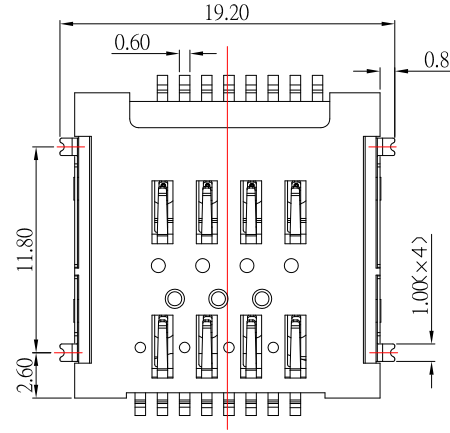
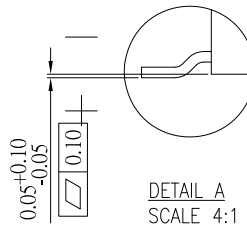


SECTION B-B



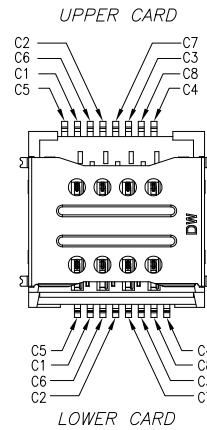
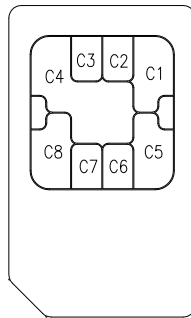
DETAIL A



P.C.B LAYOUT MOUNTING PATTERN

C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED

SIM CARD CIRCUIT



MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : COPPER ALLOY
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. INSULATION RESISTANCE : 1000MΩ MIN.
2. CONTACT RESISTANCE : 50mΩ MAX.
3. Dielectric Withstanding Voltage: 350V AC
4. Durability: 3000 cycles



TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
 CHECKED BY: Jacky Chen
 APPROVED BY: Tony Kao

DATE: 02/27/19
 DATE: 02/27/19
 DATE: 02/27/19

MAT'L
 FINISH
 SCALE: 1 : 1
 SHEET NO.: 1 of 1

TITLE: CONNECTOR
 MODLE: 雙層SIM卡座H3.0
 DWG NO.: SIM-216D202-S267
 PART NO.: SIM-216D202-S267

SIZE: A4
 VER: R

ITEM NO.	DESCRIPTION	DRAWN	DATE